

**In the Claims:**

**Please enter the following amended claims 1, 17, and 44:**

C<sup>1</sup>

1. (Once Amended) A structure comprising:

- a substrate having a top surface for receiving a die;
- a printed circuit board attached to a bottom surface of said substrate;
- a support pad attached to said top surface of said substrate, said support pad being situated underneath said die, said support pad being coupled to said die by a down bonding wire;
- at least one via in said substrate;
- said at least one via providing an electrical connection between a signal bond pad of said die and said printed circuit board.

C<sup>2</sup>

17. (Once Amended) A structure comprising:

- a substrate having a top surface and a bottom surface;
- a semiconductor die attached to said top surface of said substrate;
- a heat spreader attached to said bottom surface of said substrate;
- a support pad attached to said top surface of said substrate, said support pad being connected to said heat spreader;
- a first via in said substrate;

Cont'd  
C2 said first via providing a connection between said semiconductor die and said heat spreader.

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44. (Once Amended) A structure comprising:

a substrate having a top surface and a bottom surface;

a semiconductor die attached to said top surface of said substrate;

a heat spreader attached to said bottom surface of said substrate;

C3 a support pad attached to said top surface of said substrate, said support pad being connected to said heat spreader;

a first plurality of vias in said substrate;

said first plurality of vias providing a connection between said semiconductor die and said heat spreader.

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